

Norme e Pubblicazioni Europee recepite mediante segnalazione su CEINFORMA/CEI Magazine

Di seguito viene riportato un elenco di Norme e Pubblicazioni Europee pubblicate dal CENELEC, suddivise per CT CEI, TC CENELEC o TC IEC, che, stante l'interesse limitato a settori specialistici, sono state recepite con la segnalazione, fino a tutto il 2007, mediante l'organo ufficiale del Comitato Elettrotecnico Italiano "CEINFORMA", da gennaio 2008 sostituito dal nuovo periodico del CEI, CEI Magazine-Aggiornamenti Normativi. Le stesse sono disponibili nella sola versione originale cartacea e in generale, per quanto riguarda le Norme europee (EN), vengono vendute unitamente alla pubblicazione IEC cui fanno riferimento.

Per l'elenco completo delle Norme emesse dal Comitato per i Componenti Elettronici del CENELEC (Sigla CECC o EN serie 100000), solo in minima parte presenti in questa Sezione del Catalogo generale CEI, si consulti il Catalogo CENELEC in vigore, accessibile anche all'indirizzo: www.cenelec.eu.

Per informazioni circa l'acquisto rivolgersi all'Ufficio Vendite.
31-07-2009

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| CEI/CT 3/16 | Strutture delle informazioni, documentazioni, segni grafici, contrassegni e altre identificazioni (ex CT 3, ex CT 16) |
| EN 80416-2:2001-08 | Basic principles for graphical symbols for use on equipment Part 2: Form and use of arrows |
| CEI/CT 4/5 | Motori primi idraulici e turbine a vapore (Ex CT 4, CT 5) |
| EN 60609-1:2005-01 | Hydraulic turbines, storage pumps and pump-turbines - Cavitation pitting evaluation Part 1: Evaluation in reaction turbines, storage pumps and pump-turbines |
| EN 61063:1996-01 | Acoustics - Measurement of airborne noise emitted by steam turbines and driven machinery |
| CEI/CT 9 | Sistemi e componenti elettrici ed elettronici per trazione |
| EN 50122-2/A1:2002-04 | Railway applications - Fixed installations Part 2: Protective provisions against the effects of stray currents caused by d.c. traction systems |
| <i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 50122-2:1996 (CEI 9-6/2) nella Sezione "Webstore/Catalogo CEI" (ricerca per classificazione CEI oppure per numerazione EN nei campi "Norma Italiana" o "Norma Europea").</i> | |
| CEI/CT 14 | Trasformatori |
| EN 60076-1/A1:2000-11 | Power transformers Part 1: General |
| <i>Per la Norma base cui il presente Amendment si riferisce- sostitutivo della EN 60076-1/A11:1997-12 -, si veda la CEI EN 60076-1:1998 (CEI 14-4/1) nella Sezione "Webstore/Catalogo CEI" (ricerca per classificazione CEI oppure per numerazione EN nei campi "Norma Italiana" o "Norma Europea").</i> | |
| CEI/CT 17 | Grossa apparecchiatura |
| EN 60439-3/EC2:2005-12 | Low-voltage switchgear and controlgear assemblies Part 3: Particular requirements for low-voltage switchgear and controlgear assemblies intended to be installed in places where unskilled persons have access for their use - Distribution boards |
| <i>Per la Norma base cui il presente Corrigendum si riferisce si veda la CEI EN 60439-3:1997 (CEI 17-13/3) nella Sezione "Webstore/Catalogo CEI" (ricerca per classificazione CEI oppure per numerazione EN nei campi "Norma Italiana" o "Norma Europea").</i> | |
| CEI/CT 20 | Cavi per energia |
| HD 635 S1:1997-12 | Tests on external gas-pressure (gas compression) cables and accessories for alternating voltages up to 275 kV (Um = 300 kV) |
| HD 634 S1:1997-12 | Tests on internal gas-pressure cables and accessories for alternating voltages up to 275 kV (Um = 300 kV) |
| CEI/CT 22 | Elettronica di potenza |
| EN 60633:1999-01 | Terminology for high-voltage direct current (HVDC) transmission |
| EN 60700-1:1998-10 | Thyristor valves for high voltage direct current (HVDC) power transmission Part 1: Electrical testing |
| EN 60700-1/A1:2003-04 | Thyristor valves for high voltage direct current (HVDC) power transmission Part 1: Electrical testing |
| EN 61803:1999-04 (+ IEC 61803/Ec:1999-10) | Determination of power losses in high-voltage direct current (HVDC) converter stations |
| EN 61954:1999-11 (+ IEC 61954/Ec:1999-12) | Power electronics for electrical transmission and distribution systems Testing of thyristor valves for static VAR compensators |
| EN 61954/A1:2003-04 | Power electronics for electrical transmission and distribution systems -Testing of thyristor valves for static VAR compensators |
| TR 60919-1:2005-12 | Performance of high-voltage direct current (HVDC) systems with line-commutated converters Part 1: Steady-state conditions |

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| CEI/CT 23 | Apparecchiatura a bassa tensione |
| EN 196500/A1:2001-08 | Sectional Specification: Membrane switches including Blank Detail Specification EN 196501 |
| CEI/CT 31 | Materiali antideflagranti |
| ENV 50269:1997-02 | Assessment and representative testing of high-voltage machines |
| ENV 50269/EC:1997-03 | Assessment and representative testing of high-voltage machines |
| TR 50426:2004-12 | Assessment of inadvertent initiation of bridge wire electro-explosive devices by radio-frequency radiation - Guide |
| TR 50427:2004-12 | Assessment of inadvertent ignition of flammable atmospheres by radio-frequency radiation - Guide |
| CEI/CT 34 | Lampade e relative apparecchiature |
| EN 60400/A1/EC:2003-07 | Lampolders for tubular fluorescent lamps and starterholders |
| <i>Il presente Corrigendum si riferisce alla CEI EN 60400/A1:2003-03 (CEI 34-14 V1).</i> | |
| CEI/CT 44 | Equipaggiamento elettrico delle macchine industriali |
| CLC/TS 61496-3:2008-05 | Safety of machinery - Electro-sensitive protective equipment Part 3: Particular requirements for Active Opto-electronic Protective Devices responsive to Diffuse Reflection (AOPDDR) |
| <i>Da utilizzare congiuntamente alla EN 61496-1.</i> | |
| CEI/CT 45/345 | Strumentazione nucleare (ex CT 45, CT 345) |
| EN 60325:2004-07 | Radiation protection instrumentation - Alpha, beta and alpha/beta (beta energy > 60 keV) contamination meters and monitors |
| EN 60761-1:2004-12 | Equipment for continuous monitoring radioactivity in gaseous effluents Part 1: General requirements |
| EN 60761-2:2004-12 | Equipment for continuous monitoring radioactivity in gaseous effluents Part 2: Specific requirements for aerosols monitors including transuranic aerosols |
| EN 60761-3:2004-12 | Equipment for continuous monitoring radioactivity in gaseous effluents Part 3: Specific requirements for radioactive noble gas monitors |
| EN 60761-4:2004-12 | Equipment for continuous monitoring radioactivity in gaseous effluents Part 4: Specific requirements for iodine monitors |
| EN 60761-5:2004-12 | Equipment for continuous monitoring radioactivity in gaseous effluents Part 5: Specific requirements for tritium monitors |
| EN 60846:2004-11 | Radiation protection instrumentation - Ambient and/or directional dose equivalent (rate) meters and/or monitors for beta, X and gamma radiation |
| EN 61005:2004-11 | Radiation protection instrumentation - Neutron ambient dose equivalent (rate) meters |
| CEI/CT 46 | Cavi simmetrici e coassiali, cordoni, fili, guide d'onda, connettori per radiofrequenza |
| CECC 299001:1999-04 | Technology Approval Schedule: Manufacture of electrical connectors |
| <i>Norma elaborata congiuntamente dal CT 46 e CT 48.</i> | |
| EN 50289-1-13:2004-03 | Communication cables - Specifications for test methods Part 1-13: Electrical test methods - Coupling attenuation or screening attenuation of patch cords / coaxial cable assemblies / pre-connectorised cables |
| EN 50289-1-14:2004-03 | Communication cables - Specifications for test methods Part 1-14: Electrical test methods - Coupling attenuation or screening attenuation of connecting hardware |
| EN 50289-1-15:2004-06 | Communication cables - Specifications for test methods Part 1-15: Electromagnetic performance - Coupling attenuation of links and channels (Laboratory conditions) |
| EN 50289-4-12:2004-06 | Communication cables - Specifications for test methods Part 4-12: Environmental test methods - Vertical flame spread test on bunched small communication cables |
| EN 50406-1:2004-06 | End user multi-pair cables used in high bit rate telecommunication networks Part 1: Aerial cables |
| EN 50406-2:2004-06 | End user multi-pair cables used in high bit rate telecommunication networks Part 2: Duct and buried cables |
| EN 50407-1:2004-06 | Multi-pair cables used in high bit rate digital access telecommunication networks Part 1: Outdoor cables |
| EN 60154-2:1997-07 (+ IEC 60154-2/EC:1981-11) | Flanges for waveguides Part 2: Relevant specifications for flanges for ordinary rectangular waveguides |
| EN 60154-2/A1:1997-07 | Flanges for waveguides Part 2: Relevant specifications for flanges for ordinary rectangular waveguides |

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| EN 61196-4:2004-03 | Coaxial communication cables Part 4: Sectional specification for radiating cables |
| EN 61726:2000-03 | Cable assemblies, cables, connectors and passive microwave components - Screening attenuation measurement by the reverberation chamber method |
| EN 62037:1999-11 | RF connectors, connector cable assemblies and cables - Intermodulation level measurement |
| EN 62153-1-1:2004-01 | Metallic telecommunication cables test methods Part 1-1: Electrical - Measurement of the pulse/step return loss in the frequency domain using the Inverse Discrete Fourier Transformation (IDFT) |
| EN 62153-4-2:2004-01 | Metallic telecommunication cable test methods Part 4-2: Electromagnetic compatibility (EMC) - Screening and coupling attenuation - Injection clamp method |
| CEI/CT 48 | Componenti elettromeccanici per apparecchiature elettroniche |
| EN 60297-3-101:2004-09 | Mechanical structures for electronic equipment - Dimensions of mechanical structures of the 482,6 mm (19 in) series Part 3-101: Subracks and associated plug-in units |
| EN 60297-3-102:2004-09 | Mechanical structures for electronic equipment - Dimensions of mechanical structures of the 482,6 mm (19 in) series Part 3-102: Injector/extractor handle |
| EN 60297-3-103:2004-09 | Mechanical structures for electronic equipment - Dimensions of mechanical structures of the 482,6 mm (19 in) series Part 3-103: Keying and alignment pin |
| EN 60297-3-104:2006-06 | Mechanical structures for electronic equipment - Dimensions of mechanical structures of the 482,6 mm (19 in) series Part 3-104: Connector dependent interface dimensions of subracks and plug-in units |
| EN 60512-11-1:1999-11 | Electromechanical components for electronic equipment - Basic testing procedures and measuring methods Part 11: Climatic tests Section 1: Test 11a - Climatic sequence |
| EN 60512-11-8:1999-01 | Electromechanical components for electronic equipment - Basic testing procedures and measuring methods Part 11: Climatic tests Section 8: Test 11h - Sand and dust |
| EN 60512-14-7:1998-02 | Electromechanical components for electronic equipment - Basic testing procedures and measuring methods Part 14: Sealing tests Section 7: Test 14g: Impacting water |
| EN 60603-3:1998-02 | Connectors for frequencies below 3 MHz for use with printed boards Part 3: Two-part connectors for printed boards having contacts spaced at 2,54 mm (0,100 in) centres and staggered terminations at that same spacing |
| EN 60603-4:1998-02 | Connectors for frequencies below 3 MHz for use with printed boards Part 4: Two-part connectors for printed boards having contacts spaced at 1,91 mm (0,075 in) centres and staggered terminations at that same spacing |
| EN 60603-5:1998-02 | Connectors for frequencies below 3 MHz for use with printed boards Part 5: Edge-socket connectors and two-part connectors for double-sided printed boards with 2,54 mm (0,1 in) spacing |
| EN 60603-6:1998-02 | Connectors for frequencies below 3 MHz for use with printed boards Part 6: Edge-socket connectors and printed-board connectors with 2,54 mm (0,1 in) contact spacing for single or double-sided printed boards of 1,6 mm (0,063 in) nominal thickness |
| EN 60603-8:1998-02 | Connectors for frequencies below 3 MHz for use with printed boards Part 8: Two-part connectors for printed boards, for basic grid of 2,54 mm (0,1 in), with square male contacts of 0,63 mm x 0,63 mm |
| EN 60603-9:1998-02 | Connectors for frequencies below 3 MHz for use with printed boards Part 9: Two-part connectors for printed boards, backpanels and cable connectors, basic grid of 2,54 mm (0,1 in) |
| EN 60603-10:1998-02 | Connectors for frequencies below 3 MHz for use with printed boards Part 10: Two-part connectors for printed boards for basic grid of 2,54 mm (0,1 in), inverted type |
| EN 60603-12:1998-02 | Connectors for frequencies below 3 MHz for use with printed boards Part 12: Detail specification for dimensions, general requirements and tests for a range of sockets designed for use with integrated circuits |
| EN 60603-13:1998-02 | Connectors for frequencies below 3 MHz for use with printed boards Part 13: Detail specification for two-part connectors of assessed quality, for printed boards for basic grid of 2,54 mm (0,1 in), with free connectors for non-accessible insulation displacement terminations (ID) |
| EN 61076-2:1999-04 | Connectors for use in d.c., low-frequency analogue and in digital high-speed data applications Part 2: Circular connectors with assessed quality - Sectional specification Sectional specification |
| EN 61076-2-001:2001-12 | Connectors for electronic equipment Part 2-001: Circular connectors - Blank detail specification |
| EN 61076-2-103:2004-05 | Connectors for electronic equipment Part 2-103: Circular connectors - Detail specification for a range of multipole connectors (type 'XLR') |
| EN 61076-3-001:2000-01 | Connectors for use in d.c., low frequency analogue, and digital high speed data applications Part 3-001: Rectangular connectors with assessed quality - Blank detail specification |
| EN 61076-3-100:2000-01 | Connectors for use in d.c., low-frequency analogue and digital high speed data applications Part 3-100: Rectangular connectors with assessed quality Detail specification for a range of shielded connectors with trapezoidal-shaped shells and non-removable ribbon contacts on a 1,27 mm double row |

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| EN 61076-3-103:2004-02 | Connectors for electronic equipment Part 3-103: Rectangular connectors - Detail specification for single row connectors with non-removable ribbon cable contacts on 1,25 mm pitch used for high speed serial data (HSSDC) |
| EN 61076-4-101:2001-10 (+ IEC 61076-4-101/Ec:2003-11) | Connectors for electronic equipment Part 4-101: Printed board connectors with assessed quality - Detail specification for two-part connector modules, having a basic grid of 2,0 mm for printed boards and backplanes in accordance with IEC 60917 |
| EN 61076-4-107:2001-10 | Connectors for electronic equipment Part 4-107: Printed board connectors with assessed quality - Detail specification for shielded two-part connectors having a basic grid of 2,0 mm, fixed part with solder and press-in terminations for printed boards, free part with non-accessible insulation displacement and crimp terminations |
| EN 61076-4-113:2003-02 | Connectors for electronic equipment - Printed board connectors Part 4-113: Detail specification for two-part connectors having 5 rows with a grid of 2,54 mm for printed boards and backplanes in bus applications |
| EN 61076-5:2001-10 | Connectors for use in DC, low-frequency analogue and digital high-speed data application Part 5: In-line sockets with assessed quality - Sectional Specification Sectional Specification |
| EN 61076-7-001:2004-09 | Connectors for electronic equipment Part 7-001: Cable outlet accessories - Blank detail specification |
| EN 175101-802:1999-11 | Detail specification: Two-part connectors for printed boards for high number of contacts with basic grid of 2,54 mm on 3 or 4 rows art connectors for printed boards for high number of contacts with basic grid of 2,54 mm on 3 or 4 rows |
| EN 175101-809:2004-03 | Detail specification: Two-part connectors for printed boards having a grid of 2,54 mm, short version in compliance with CECC 75 101-801, with assessed quality art connectors for printed boards having a grid of 2,54 mm, short version in compliance with CECC 75 101-801, with assessed quality |
| EN 175101-809:2004/EC:2005-06 | Detail specification: Two-part connectors for printed boards having a grid of 2,54 mm, short version in compliance with CECC 75 101-801, with assessed quality art connectors for printed boards having a grid of 2,54 mm, short version in compliance with CECC 75 101-801, with assessed quality |
| EN 175201-804:1999-11 | Detail Specification: Circular connectors - Round contacts, size diameter 1,6 mm, threaded coupling |
| CEI/CT 57 | Scambio informativo associato alla gestione dei sistemi elettrici di potenza |
| EN 60870-5-103:1998-02 | Telecontrol equipment and systems Part 5: Transmission protocols Section 103: Companion standard for the informative interface of protection equipment |
| EN 60870-6-701:1998-10 | Telecontrol equipment and systems Part 6: Telecontrol protocols compatible with ISO standards and ITU-T recommendations Section 701: Functional profile for providing the TASE.1 application service in end systems |
| EN 60870-6-702:1998-11 | Telecontrol equipment and systems Part 6: Telecontrol protocols compatible with ISO standards and ITU-T recommendations Section 702: Functional profile for providing the TASE.2 application service in end systems |
| EN 61334-4-512:2002-02 | Distribution automation using distribution line carrier systems Part 4-512: Data Communication Protocols -Systems management using profile 61334-5-1 - Management information base (MIB) |
| EN 61850-6:2004-05 | Communication networks and systems in substations Part 6: Configuration description language for communication in electrical substations related to IEDs |
| EN 61850-8-1:2004-06 | Communication networks and systems in substations Part 8-1: Specific communication service mapping (SCSM) - Mapping to MMS (ISO/IEC 9506 Part 1 and Part 2) over ISO 8802-3 |
| EN 61850-9-2:2004-05 | Communication networks and systems in substations Part 9-2: Specific Communication System Mappings (SCSM) - Sampled values over ISO/IEC 8802-3 |
| EN 61968-1:2004-01 | Application integration at electric utilities - System interfaces for distribution management Part 1: Interface architecture and general requirements |
| EN 61968-3:2004-06 | Application integration at electric utilities - System interfaces for distribution management Part 3: Interface for network operations |
| EN 61968-4:2007-08 | Application integration at electric utilities - System interfaces for distribution management Part 4: Interfaces for records and asset management |
| EN 61970-301:2004-03 | Energy management system application program interface (EMS-API) Part 301: Common Information Model (CIM) Base |

| CEI/CT 59/61 | Apparecchi utilizzatori elettrici per uso domestico e similare (ex CT 107) |
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| EN 61029-2-8:2003-10 | Safety of transportable motor-operated electric tools Part 2: Particular requirements for single spindle vertical moulders |
| EN 50144-2-16:2003-07 | Safety of hand-held electric motor operated tools Part 2: Particular requirements for tackers |
| EN 60335-1:1994/A2:2000/EC:2004-02 | Household and similar electrical appliances - Safety Part 1: General requirements |
| <i>Per la Norma base cui il presente Corrigendum si riferisce si veda la CEI EN 60335-1:1994/A2/A16:2002 (CEI 61-150:1998; V3:2002) nella Sezione "Webstore/Catalogo CEI" (ricerca per classificazione CEI oppure per numerazione EN nei campi "Norma Italiana" o "Norma Europea").</i> | |
| EN 60335-2-91:2003-07 | Household and similar electrical appliances - Safety Part 2-91: Particular requirements for walk-behind and hand-held lawn trimmers and lawn edge trimmers |
| EN 60730-1/EC:1997-04 | Automatic electrical controls for household and similar use - Part 1: General requirements |
| <i>Per la Norma base cui il presente Corrigendum si riferisce si veda la CEI EN 60730-1:1996 (CEI 72-2) nella Sezione "Webstore/Catalogo CEI" (ricerca per classificazione CEI oppure per numerazione EN nei campi "Norma Italiana" o "Norma Europea").</i> | |
| EN 61029-2-11:2003-11 | Safety of transportable motor-operated electric tools Part 2-11: Particular requirements for mitre-bench saws |
| CEI/CT 65 | Misura, controllo e automazione nei processi industriali |
| EN 50325-1:2002-12 | Sottosistema di comunicazione industriale basato su ISO 11898 (CAN) per le interfacce controllore-dispositivo Parte 1: Requisiti generali |
| EN 50325-4:2002-12 | Sottosistema di comunicazione industriale basato su ISO 11898 (CAN) per le interfacce controllore-dispositivo Parte 4: CANopen |
| EN 61131-3:2003-03 | Controllori programmabili Parte 3: Linguaggi di programmazione |
| EN 61512-1:1999-06 | Controllo lotti Parte 1: Modelli e terminologia |
| EN 61512-2:2002-10 | Controllo lotti Parte 2: Struttura dei dati e linee guida per i linguaggi |
| TR 61158-1:2004-07 | Comunicazioni di dati digitali per la misura e il controllo - Bus di campo per l'uso nei sistemi di controllo industriali Parte 1: Panorama e linee guida della serie IEC 61158 |
| CEI/CT 82 | Sistemi di conversione fotovoltaica dell'energia solare |
| EN 60904-10:1998-04 | Photovoltaic devices Part 10: Methods of linearity measurement |
| CEI/CT 86 | Fibre ottiche |
| CECC 78005-802:1999-05 | Specifica di dettaglio: Terminazioni di qualità assicurata per fibre ottiche e cavi - Tipo LSD-HRL |
| EN 50377-5-1:2003-03 | Connettori e dispositivi di interconnessione da utilizzare nei sistemi di comunicazione in fibra ottica - Specifiche di prodotto Parte 5-1: Tipo EC terminato su fibre monomodali di categoria B1.1 conformi alla Norma IEC 60793-2 |
| EN 50377-6-1:2002-09 | Connettori e dispositivi di interconnessione da utilizzare nei sistemi di comunicazione in fibra ottica - Specifiche di prodotto Parte 6-1: Tipo SC-RJ terminato su fibre multimodali di categoria A1a e A1b conformi alla Norma IEC 60793-2 |
| <i>ATTENZIONE: Contiene immagini a colori.</i> | |
| EN 50377-6-2:2007-08 | Connettori e dispositivi di interconnessione da utilizzare nei sistemi di comunicazione in fibra ottica - Specifiche di prodotto Parte 6-2: Connettori di tipo SC-RJ terminati su fibre monomodo di categoria B1.1 e B.1.3 conformi alla Norma IEC 60793-2-50, per Categoria U |
| <i>ATTENZIONE: Contiene immagini a colori.</i> | |
| EN 50377-7-1:2004-05 | Connettori e dispositivi di interconnessione da utilizzare nei sistemi di comunicazione in fibra ottica - Specifiche di prodotto Parte 7-1: Tipo LC-PC duplex terminato su fibre multimodali di categoria A1a e A1b conformi alla Norma IEC 60793-2 |
| <i>ATTENZIONE: Contiene immagini a colori.</i> | |
| EN 50377-7-2:2004-05 | Connettori e dispositivi di interconnessione da utilizzare nei sistemi di comunicazione in fibra ottica - Specifiche di prodotto Parte 7-2: Tipo LC-PC duplex terminato su fibre monomodali di categoria B1.1 conformi alla Norma IEC 60793-2 |
| <i>ATTENZIONE: Contiene immagini a colori.</i> | |
| EN 50377-7-3:2004-05 | Connettori e dispositivi di interconnessione da utilizzare nei sistemi di comunicazione in fibra ottica - Specifiche di prodotto Parte 7-3: Tipo LC-APC duplex terminato su fibre monomodali di categoria B1.1 conformi alla Norma IEC 60793-2 |
| <i>ATTENZIONE: Contiene immagini a colori.</i> | |

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| EN 50377-7-4:2004-05 | Connector sets and interconnect components to be used in optical fibre communication systems - Product specifications Part 7-4: LC-PC simplex terminated on IEC 60793-2 category B1.1 singlemode fibre |
| EN 50377-9-1:2003-05 | Connettori e dispositivi di interconnessione da utilizzare nei sistemi di comunicazione in fibra ottica - Specifiche di prodotto Parte 9-1: Tipo MT-RJ terminato su fibre multimodali di categoria A1a e A1b conformi alla Norma IEC 60793-2 |
| EN 50377-9-2:2004-03 | Connettori e dispositivi di interconnessione da utilizzare nei sistemi di comunicazione in fibra ottica - Specifiche di prodotto Parte 9-2: Tipo MT-RJ terminato su fibre monomodali di categoria B1.1 conformi alla Norma IEC 60793-2 |
| <i>ATTENZIONE: Contiene immagini a colori.</i> | |
| EN 50377-10-1:2007-08 | Connettori e dispositivi di interconnessione da utilizzare nei sistemi di comunicazione in fibra ottica - Specifiche di prodotto Parte 10-1: Tipo MU-PC singolo terminato su fibre monomodo di categoria B1.1 e B1.3 conformi alla Norma IEC 60793-2-50, con ferula tutta in zirconia, per Categoria C |
| <i>ATTENZIONE: Contiene immagini a colori.</i> | |
| EN 60793-1-20:2002-03 | Fibre ottiche Parte 1-20: Metodi di misura e procedure di prova - Geometria della fibra |
| EN 60793-1-21:2002-03 | Fibre ottiche Parte 1-21: Metodi di misura e procedure di prova - Geometria del rivestimento |
| EN 60793-1-22:2002-03 | Fibre ottiche Parte 1-22: Metodi di misura e procedure di prova - Misura della lunghezza |
| EN 60793-1-31:2002-02 | Fibre ottiche Parte 1-31: Metodi di misura e procedure di prova - Resistenza alla trazione |
| EN 60793-1-32:2003-12 | Fibre ottiche Parte 1-32: Metodi di misura e procedure di prova - Asportabilità del rivestimento |
| EN 60793-1-33:2002-04 | Fibre ottiche Parte 1-33: Metodi di misura e procedure di prova - Resistenza alla corrosione sotto stress |
| EN 60793-1-40:2003-12 | Fibre ottiche Parte 1-40: Metodi di misura e procedure di prova - Attenuazione |
| EN 60793-1-41:2003-12 | Fibre ottiche Parte 1-41: Metodi di misura e procedure di prova - Larghezza di banda |
| EN 60793-1-43:2002-02 | Fibre ottiche Parte 1-43: Metodi di misura e procedure di prova - Apertura numerica |
| EN 60793-1-44:2002-02 | Fibre ottiche Part 1-44: Metodi di misura e procedure di prova - Lunghezza d'onda di taglio |
| EN 60793-1-45:2003-12 + EC:2004-04 | Fibre ottiche Parte 1-45: Metodi di misura e procedure di prova - Diametro del campo modale |
| EN 60793-1-46:2002-02 | Fibre ottiche Parte 1-46: Metodi di misura e procedure di prova - Controllo delle variazioni del fattore di trasmissione ottico |
| EN 60793-1-50:2002-02 | Fibre ottiche Parte 1-50: Metodi di misura e procedure di prova - Caldo umido (stato permanente) |
| EN 60793-1-51:2002-02 | Fibre ottiche Parte 1-51: Metodi di misura e procedure di prova - Caldo secco |
| EN 60793-1-52:2002-02 | Fibre ottiche Parte 1-52: Metodi di misura e procedure di prova - Variazioni di temperatura |
| EN 60793-1-53:2002-02 | Fibre ottiche Parte 1-53: Metodi di misura e procedure di prova - Immersione in acqua |
| EN 60793-1-54:2003-11 | Fibre ottiche Parte 1-54: Metodi di misura e procedure di prova - Radiazioni gamma |
| EN 60794-1-1:2002-02 | Cavi in fibra ottica Parte 1-1: Specifica generica - Generalità |
| EN 60794-1-2:2003-11 | Cavi in fibra ottica Parte 1-2: Specifica generica - Procedure di prova fondamentali per cavi ottici |
| EN 60794-3:2002-03 | Cavi in fibra ottica Parte 3: Specifiche settoriali - Cavi da esterni |
| <i>ATTENZIONE: Contiene immagini a colori.</i> | |
| EN 60794-3-10:2002-06 | Optical fibre cables Part 3-10: Outdoor cables - Family specification for duct and directly buried optical telecommunication cables |
| EN 60794-3-20:2002-06 | Optical fibre cables Part 3-20: Outdoor cables - Family specification for optical self-supporting aerial telecommunication cables |
| EN 60794-4:2003-11 | Cavi in fibra ottica Parte 4: Specifica settoriale - Cavi ottici aerei posati lungo linee elettriche di energia |

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| EN 61280-1-4:2003-04 | Fibre optic communication subsystem basic test procedures Part 1-4: General communication subsystems - Collection and reduction of two-dimensional nearfield data for multimode fibre laser transmitters |
| EN 61280-2-8:2003-04 | Procedura di prova per sottosistemi di telecomunicazione in fibra ottica - Sistemi numerici Parte 2-8: Determinazione dei bassi valori di BER attraverso misure del fattore Q |
| <i>ATTENZIONE: Contiene immagini a colori.</i> | |
| EN 61280-2-9:2002-12 | Fibre optic communication subsystem test procedures Part 2-9: Digital systems - Optical signal-to-noise ratio measurement for dense wavelength-division multiplexed systems |
| EN 61280-4-1:2004-05 | Fibre optic communication subsystem test procedures Part 4-1: Cable plant and links - Multimode fibre-optic cable plant attenuation measurement |
| EN 61290-3-1:2003-11 | Amplificatori Ottici - Metodi di prova Parte 3-1: Parametri di rumore - Metodo dell'analizzatore di spettro ottico |
| EN 61290-5-2:2004-05 | Amplificatori Ottici - Metodi di prova Parte 5-2: Parametri di riflettanza - Metodo dell'analizzatore di spettro elettrico |
| EN 61290-5-3:2002-04 | Amplificatori ottici - Specifica di base Parte 5-3: Metodi di prova dei parametri di riflettanza - Tolleranza alla riflettanza tramite l'analizzatore di spettro elettrico |
| EN 61290-10-1:2003-07 | Optical amplifiers - Test methods Part 10-1: Multichannel parameters - Pulse method using an optical switch and optical spectrum analyzer |
| EN 61290-10-2:2003-07 | Optical amplifier - Test methods Part 10-2: Multichannel parameters - Pulse method using a gated optical spectrum analyzer |
| EN 61290-10-3:2003-07 | Amplificatori ottici - Metodi di prova Parte 10-3: Parametri del funzionamento in multicanale - Metodi della sonda ottica |
| EN 61290-11-1:2003-04 | Optical amplifier test methods Part 11-1: Polarization mode dispersion - Jones matrix eigenanalysis method (JME) |
| EN 61291-4:2003-06 | Optical amplifiers -- Part 4: Multichannel applications - Performance specification template Part 4: Multichannel applications - Performance specification template |
| EN 61291-5-2:2002-12 | Amplificatori ottici Parte 5-2: Specifiche di qualificazione - Qualificazione di affidabilità per amplificatori ottici |
| EN 61300-1:2003-11 | Dispositivi di interconnessione e componenti passivi per fibre ottiche - Procedure di prova e di misura fondamentali Parte 1: Generalità e guida |
| EN 61300-2-17:2003-04 | Dispositivi di interconnessione e componenti passivi per fibre ottiche - Procedure di prova e di misura fondamentali Parte 2-17: Prove - Freddo |
| EN 61300-2-2:2003-04 (+ IEC 61300-2-2/EC1:2004-04) | Fibre optic interconnecting devices and passive components - Basic test and measurement procedures Part 2-2: Tests - Mating durability |
| EN 61300-2-48:2003-04 (+ IEC 61300-2-48/EC1:2004-04) | Fibre optic interconnecting devices and passive components - Basic test and measurement procedures Part 2-48: Tests - Temperature-humidity cycling |
| EN 61300-2-5:2002-12 | Dispositivi di interconnessione e componenti passivi per fibre ottiche - Procedure di prova e di misura fondamentali Parte 2-5: Prove - Torsione |
| EN 61300-3-26:2002-11 | Dispositivi di interconnessione e componenti passivi per fibre ottiche - Procedure di prova e di misura fondamentali Parte 3-26: Esami e misure - Misura del disallineamento angolare tra gli assi della fibra e della ferula |
| EN 61300-3-3:2003-04 | Fibre optic interconnecting devices and passive components - Basic test and measurement procedures Part 3-3: Examinations and measurements - Active monitoring of changes in attenuation and return loss |
| EN 61300-3-31:2003-04 | Dispositivi di interconnessione e componenti passivi per fibre ottiche - Procedure di prova e di misura fondamentali Parte 3-31: Esami e misure - Misura del rapporto di potenza accoppiata da sorgenti per fibre ottiche |
| EN 61300-3-6:2003-04 | Fibre optic interconnecting devices and passive components - Basic test and measurement procedures Part 3-6: Examinations and measurements - Return loss |
| EN 61753-021-2:2002-09 | Fibre optic interconnecting devices and passive component performance standard Part 021-2: Fibre optic connectors terminated on single-mode fibre for category C - Controlled environment |
| EN 61753-022-2:2003-04 | Norma di prestazione di dispositivi di interconnessione e componenti passivi per fibre ottiche Parte 022-2: Connettori ottici terminati su fibre ottiche multimodali per categoria C - Ambiente controllato |
| EN 61753-051-3:2002-03 (+ IEC 61753-051-3/EC1:2004-10) | Norma di prestazione di dispositivi di interconnessione e componenti passivi per fibre ottiche Parte 051-3: Attenuatori fissi a connettore (plug-style) per fibra monomodale per categoria U - Ambiente non controllato |
| EN 61753-052-3:2002-03 | Norma di prestazione di dispositivi di interconnessione e componenti passivi per fibre ottiche Parte 052-3: Attenuatori fissi con codino (pigtailed-style) per fibra monomodale per categoria U - Ambiente non controllato |
| EN 61753-053-3:2004-03 | Norma di prestazione di dispositivi di interconnessione e componenti passivi per fibre ottiche Parte 053-3: Attenuatori variabili con continuità per categoria U - Ambiente non controllato |
| EN 61753-061-3:2004-10 | Norma di prestazione di dispositivi di interconnessione e componenti passivi per fibre ottiche Parte 061-3: Isolatori con codino (pigtail) per fibre ottiche monomodali per categoria U - Ambiente non controllato |
| EN 61753-091-3:2004-10 | Norma di prestazione di dispositivi di interconnessione e componenti passivi per fibre ottiche Parte 091-3: Circolatori con codino (pigtail) per fibre ottiche monomodali per categoria U - Ambiente non controllato |

Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 61754-6:1998 (CEI 86-75) nella Sezione "Webstore/Catalogo CEI" (ricerca per classificazione CEI oppure per numerazione EN nei campi "Norma Italiana" o "Norma Europea").

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| EN 61977:2002-03 | Filtri per fibre ottiche Specifica generica |
| EN 62005-7:2004-04 | Affidabilità dei dispositivi di interconnessione e dei componenti passivi per fibra ottica Parte 7: Modellizzazione delle sollecitazioni per predire il tempo di vita |
| EN 62134-1:2002-05 | Fibre optic enclosures - Generic specification |
| EN 62148-1:2002-04 | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 1: Generalità e linee guida |
| EN 62148-2:2003-04 (+ IEC 62148-2/EC1:2003-06) | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 2: Ricetrasmittitori SFF MT-RJ a 10 pin |
| EN 62148-3:2003-04 | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 3: Ricetrasmittitori SFF MT-RJ a 20 pin |
| EN 62148-4:2003-07 | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 4: Ricetrasmittitori PN 1x9 per fibra ottica in plastica |
| EN 62148-5:2003-04 | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 5: Moduli a fibra ottica SC 1x9 |
| EN 62148-6:2003-10 | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 6: Ricetrasmittitori ATM-PON |
| EN 62148-7:2003-04 | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 7: Ricetrasmittitori SFF LC a 10 pin |
| EN 62148-8:2003-04 | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 8: Ricetrasmittitori SFF LC a 20 pin |
| EN 62148-9:2003-04 (+ IEC 62148-9/EC1:2003-05) | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 9: Ricetrasmittitori SFF MU duplex a 10 pin |
| EN 62148-10:2003-04 | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 10: Ricetrasmittitori SFF MU duplex a 20 pin |
| EN 62148-11:2003-11 | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 11: Trasmettitori a diodo laser con modulatore integrato in contenitore a 14 pin |
| EN 62148-12:2004-04 | Componenti e dispositivi attivi a fibra ottica - Norme del contenitore e dell'interfaccia Parte 12: Trasmettitori laser con connettori coassiali a RF |
| EN 62149-1:2004-02 (+ IEC 62149-1/EC1:2004-04) | Componenti e dispositivi attivi a fibra ottica - Norme prestazionali Parte 1: Generalità e linee guida |
| EN 62149-3:2004-03 | Componenti e dispositivi attivi a fibra ottica - Standard prestazionali Parte 3: Trasmettitori a diodo laser con modulatore integrato a 2,5 Gbit/s |
| EN 62149-4:2003-05 | Componenti e dispositivi attivi a fibra ottica - Norme prestazionali Parte 4: Ricetrasmittitore a fibra ottica a 1300 nm per applicazioni di Gigabit Ethernet |
| EN 62149-5:2003-11 | Fibre optic active components and devices - Performance standards Part 5: ATM-PON transceivers with LD driver and CDR ICs |
| EN 62149-6:2003-11 | Componenti e dispositivi attivi a fibra ottica - Norme prestazionali Parte 6: Ricetrasmittitori a 250 Mbit/s con emissione a 650 nm per fibra ottica plastica |
| EN 62150-2:2004-11 | Componenti e dispositivi attivi a fibra ottica - Procedure di prova e misura Parte 2: Ricetrasmittitori ATM-PON |
| EN 181103:1997-12 | Specifica di dettaglio in bianco: Dispositivi di diramazione a fibra ottica - Tipo: Stella trasmissiva a lunghezza d'onda non selettiva per applicazioni di telecomunicazioni |
| EN 181104:1997-12 | Specifica di dettaglio in bianco: Dispositivi di diramazione a fibra ottica - Tipo: Stella trasmissiva a lunghezza d'onda selettiva per applicazioni di telecomunicazioni |
| EN 186150:1997-05 | Specifica settoriale: Connettori per fibre ottiche e cavi - Tipo OCCA-BU |
| EN 186160:1997-05 | Specifica settoriale: Connettori per fibre ottiche e cavi - Tipo OCCA-PC |
| EN 186170:1998-02 | Specifica settoriale: Connettori per fibre ottiche e cavi - Tipo RCC |
| EN 186300:1999-02 | Specifica settoriale: Connettori per fibre ottiche e cavi - Tipo MSC |
| EN 187105:2002-05 | Cavi in fibra ottica monomodali per installazione in condotte o direttamente interrati |

| CEI/CT 94 | Relé elettrici a tutto o niente (ex CT 94/95, ex CT 41) |
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| CECC 16207-804:1999-09 | Detail Specification: All-or-nothing relays for severe airborne environmental conditions 1/10 size crystal can, monostable polarized, 2 change-over contacts (2PDT), 0,5 A |
| CECC 16207-805:1999-09 | Detail Specification: All-or-nothing relays for severe airborne environmental conditions TO 5, monostable non polarized, 2 change-over contacts (2PDT), 1 A |
| CECC 16303-801:1999-09 | Detail Specification: Electromechanical all-or-nothing heavy load relays 1/2 cubic inch, monostable, 2 change-over (DPDT), 10A |
| CECC 16303-802:1999-09 | Detail Specification: Electromechanical all-or-nothing heavy load relays 1 cubic inch, monostable, 4 change-over (4PDT), 10A |
| CECC 16303-803/A1:1998-03 | Detail Specification: Electromechanical all-or-nothing heavy load relays 2/10 cubic inch, monostable, 2 change-over (DPDT), 5A |
| CECC 16303-804/A1:1998-03 | Detail Specification: Electromechanical all-or-nothing heavy load relays 4/10 cubic inch, monostable, 4 change-over (4PDT), 5 A |
| CECC 16303-805/A1:1998-03 | Detail Specification: Electromechanical all-or-nothing heavy load relays 1 cubic inch, monostable, 3 change-over (3PDT), 25A |
| CECC 16303-806/A1:1998-03 | Detail Specification: Electromechanical all-or-nothing heavy load relays 2,5 cubic inch, monostable, 6 change-over (6PDT), 10 A |
| CECC 16303-807/A1:1998-03 | Detail Specification: Electromechanical all-or-nothing heavy load relays 4/10 cubic inch, monostable, 3 change-over (3PDT), 10 A |
| CECC 16303-808/A1:1998-03 | Detail Specification: Electromechanical all-or-nothing heavy load relays 2/10 cubic inch, monostable, 1 change-over (1PDT), 10 A |
| CECC 16303-809/A1:1998-03 | Detail Specification: Electromechanical all-or-nothing heavy load relays 1/2 cubic inch, monostable, 1 change-over (1PDT), 25 A |
| CECC 16303-810:1999-09 | Detail Specification: Electromechanical all-or-nothing heavy load relays 1/2 cubic inch, bistable (magnetic latching), 2 change-over (DPDT), 10A |
| CEI/CT 100 | Sistemi e apparecchiature audio, video e multimediali (ex CT 84/60, SC 12A, SC 12G) |
| EN 50203:1996-12 | Automatic channel installations (ACI) |
| EN 50203/A1:1997-02 | Automatic channel installation (ACI) |
| EN 60094-2:1995-01 (+ IEC 60094-2/EC:1995-03) | Magnetic tape sound recording and reproducing systems - Part 2: Calibration tapes Part 2: Calibration tapes |
| EN 60094-4/A1:1994-08 | Magnetic tape sound recording and reproducing systems Part 4: Mechanical magnetic tape properties |
| <i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 60094-4:1998 (CEI 60-21) nella Sezione "Webstore/Catalogo CEI" (ricerca per classificazione CEI oppure per numerazione EN nei campi "Norma Italiana" o "Norma Europea").</i> | |
| EN 60094-5/A1:1996-03 | Magnetic tape sound recording and reproducing systems Part 5: Electrical magnetic tape properties |
| <i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 60094-5:1998 (CEI 60-22) nella Sezione "Webstore/Catalogo CEI" (ricerca per classificazione CEI oppure per numerazione EN nei campi "Norma Italiana" o "Norma Europea").</i> | |
| EN 60094-7/A1:1996-03 | Magnetic tape sound recording and reproducing systems Part 7: Cassette for commercial tape records and domestic use |
| <i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 60094-7:1998 (CEI 60-28) nella Sezione "Webstore/Catalogo CEI" (ricerca per classificazione CEI oppure per numerazione EN nei campi "Norma Italiana" o "Norma Europea").</i> | |
| EN 60268-7:1996-05 | Sound system equipment Part 7: Headphones and earphones |
| EN 60268-12/A2:1995-02 | Sound system equipment Part 12: Application of connectors for broadcast and similar use |
| <i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 60268-12:1998 (CEI 84-12) nella Sezione "Webstore/Catalogo CEI" (ricerca per classificazione CEI oppure per numerazione EN nei campi "Norma Italiana" o "Norma Europea").</i> | |
| EN 60315-3:1999-04 | Methods of measurement on radio receivers for various classes of emission Part 3: Receivers for amplitude-modulated sound-broadcasting emissions |
| EN 60315-3/A1:1999-04 | Methods of measurement on radio receivers for various classes of emission Part 3: Receivers for amplitude-modulated sound-broadcasting emissions |
| EN 60315-9:1996-07 | Methods of measurement on radio receivers for various classes of emission Part 9: Measurement of the characteristics relevant to radio data system (RDS) reception |
| EN 60574-21:1993-12 | Audiovisual, video and television equipment and systems Part 21: Video tape leader and trailer for education and training applications |
| EN 60843-1:1994-04 | Helican-Scan video tape cassette system using 8 mm magnetic tape - 8 mm Video Part 1: General specifications |
| EN 60843-2:1995-06 | Helical-scan video tape cassette system using 8 mm magnetic tape - 8 mm Video Part 2: PCM multi-track audio system |

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| EN 60843-4:2000-04 | Helical-scan video tape cassette system using 8 mm magnetic tape (8 mm video) Part 4: Video subcode - VSC |
| EN 60908:1999-03 | Audio recording - Compact disc digital audio system |
| EN 60958-3:2006-10 | Digital audio interface Part 3: Consumer applications |
| EN 61096/A1:1996-12 | Methods of measuring the characteristics of reproducing equipment for digital audio compact discs |
| <i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 61096:1998 (CEI 60-41) nella Sezione "Webstore/Catalogo CEI" (ricerca per classificazione CEI oppure per numerazione EN nei campi "Norma Italiana" o "Norma Europea").</i> | |
| EN 61105:1993-10 | Reference tapes for video tape recorder systems |
| EN 61119-2:1994-07 | Digital audio tape cassette system (DAT) Part 2: DAT calibration tape |
| EN 61119-3:1994-07 | Digital audio tape cassette system (DAT) Part 3: DAT tape properties |
| EN 61119-5:1995-01 | Digital audio tape cassette system (DAT) Part 5: DAT for professional use |
| EN 61119-6:1994-07 | Digital audio tape cassette system (DAT) Part 6: Serial copy management system |
| EN 61120-3:1993-10 | Digital audio tape recorder reel to reel system, using 6.3 mm magnetic tape, for professional use Part 3: Format B |
| EN 61146-1:1996-09 | Video cameras (PAL/SECAM/NTSC) - Methods of measurement Part 1: Non-broadcast single-sensor cameras |
| EN 61213:1994-01 | Analogue audio recording on video tape - Polarity of magnetization |
| EN 61237-2:1995-06 | Broadcast video tape recorders - Methods of measurement Part 2: Electrical measurements of analogue composite video signals |
| EN 61319-1:1996-01 | Interconnections of satellite receiving equipment Part 1: Europe |
| EN 61319-1/A11:1999-04 | Interconnections of satellite receiving equipment Part 1: Europe |
| EN 61834-1:1998-10 | Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 1: General specifications |
| EN 61834-1/A1:2001-07 | Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 1: General specifications |
| EN 61834-2:1998-10 | Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 2: SD format for 525-60 and 625-50 systems |
| EN 61834-3:2000-03 | Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 3: HD format for 1125-60 and 1250-50 systems |
| EN 61834-4:1998-08 | Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 4: Packheader table and the contents |
| EN 61834-5:1998-10 | Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 5: The character information system |
| EN 61834-6:2000-11 | Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 6: SDL format |
| EN 61834-7:2001-06 | Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 7: EDTV2 format |
| EN 61834-8:2001-09 | Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 8: PALplus format for 625-50 system |
| EN 61834-9:2001-07 | Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 9: DVB format |
| EN 61834-10:2001-05 (+ IEC 61834-10/Ec1:2001-06) | Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 10: DTV format |
| EN 61834-11:2008-04 | Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 11: HDV format for 1080i and 720p systems |
| EN 61883-2:2005-11 | Consumer audio/video equipment - Digital interface Part 2: SD-DVCR data transmission |

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| EN 61883-3:2005-11 | Consumer audio/video equipment - Digital interface Part 3: HD-DVCR data transmission |
| EN 61883-4:2005-11 | Consumer audio/video equipment - Digital interface Part 4: MPEG2-TS data transmission |
| EN 61883-5:2005-11 | Consumer audio/video equipment - Digital interface Part 5: SDL-DVCR data transmission |
| EN 61883-6:2005-11 | Consumer audio/video equipment - Digital interface Part 6: Audio and music data transmission |
| EN 61883-7:2003-04 | Consumer audio/video equipment - Digital interface Part 7: Transmission of ITU-R BO.1294 System B |
| EN 61904:2000-09 | Video recording - Helical-scan digital component video cassette recording format using 12,65 mm magnetic tape and incorporating data compression (Format Digital-L) |
| EN 61937-2:2007-09 | Digital audio - Interface for non-linear PCM encoded audio bitstreams applying IEC 60958 Part 2: Burst-Info |
| EN 62071-1:2006-07 | Helical-scan compressed digital video cassette system using 6,35 mm magnetic tape - Format D-7 - Part 1: VTR specifications Part 1: VTR specifications |
| EN 62071-2:2006-07 | Helical-scan compressed digital video cassette system using 6,35 mm magnetic tape - Format D-7 - Part 2: Compression format Part 2: Compression format |
| EN 62071-3:2006-07 | Helical-scan compressed digital video cassette system using 6,35 mm magnetic tape - Format D-7 - Part 3: Data stream format Part 3: Data stream format |
| EN 62105:2002 | Digital audiobroadcast system - Specification of the receiver data interface (RDI) |
| <i>La presente Norma sostituisce la EN 50255:1997.</i> | |
| EN 62106:2001-12 | Specification of the radio data system (RDS) for VHF/FM sound broadcasting in the frequency range from 87,5 to 108,0 MHz |
| EN 62121:2001-12 | Methods of measurement for minidisc recorders /players |
| EN 62141:2006-06 | Helical-scan digital video cassette recording format using 12,65 mm magnetic tape and incorporating MPEG-4 compression - Type D-16 Format |
| EN 62156:2001-12 | Digital video recording with video compression 12,65 mm Type D-9 component format 525/60 and 625/50 (DIGITAL S) |
| EN 62261-1:2006-12 | Television METADATA Part 1: Metadata dictionary structure |
| EN 62261-2:2006-12 | Television METADATA Part 2: Data encoding protocol using key-length-value |
| EN 62289:2003-08 | Video recording - Helical-scan digital video cassette recording format using 12,65 mm magnetic tape and incorporating MPEG-2 compression - Format D-10 |
| EN 62298-4:2005-12 | TeleWeb application Part 4: Hyperteletext profile (TA 1) |
| EN 62300:2005-01 | Consumer audio/video equipment digital interface with plastic optical fibre |
| EN 62328-1:2005-09 | Multimedia home server systems - Interchangeable volume/file structure adaptation for broadcasting receivers Part 1: General description and architecture |
| EN 62328-2:2005-09 | Multimedia home server systems - Interchangeable volume/file structure adaptation for broadcasting receivers Part 2: General recording structure |
| EN 62330-1:2004-03 | Helical-scan digital video cassette recording system using 12,65 mm (0,5 in) magnetic tape - Format HD-D5 Part 1: VTR specifications |
| EN 62330-2:2004-03 | Helical-scan digital video cassette recording system using 12,65 mm (0,5 in) magnetic tape - Format HD-D5 Part 2: Compression format |
| EN 62330-3:2004-03 | Helical-scan digital video cassette recording system using 12,65 mm (0,5 in) magnetic tape - Format HD-D5 Part 3: Data stream format |
| EN 62345:2005-04 | ID format for 50 mm magneto-optical disc system |
| EN 62356-1:2004-10 | Video recording - 12,65 mm TYPE D-11 format Part 1: Tape recording |
| EN 62356-2:2004-10 | Video recording - 12,65 mm type D-11 format Part 2: Picture compression and data stream |
| EN 62356-3:2004-10 | Video recording - 12,65 mm type D-11 format Part 3: Data mapping over SDTI |
| EN 62365:2005-09 | Digital audio - Digital input-output interfacing - Transmission of digital audio over asynchronous transfer mode (ATM) networks |
| EN 62375:2004-10 | Video systems (625/50 progressive) - Video and accompanied data using the vertical blanking interval - Analogue interface |
| EN 62379-1:2007-11 | Common control interface for networked digital audio and video products Part 1: General |
| EN 62389:2006-06 | Methods of measurement for DVD players |
| EN 62403:2006-04 | High density recording format on CD-R/RW disc system - HD-BURN format |

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| CEI/CT 103 | Radiotrasmissioni (ex SC 103) |
| EN 60835-2-11:1997-01 | Methods of measurement for equipment used in digital microwave radio transmission systems Part 2: Measurements on terrestrial radio-relay systems Section 11: Cross-polarization interference canceller |
| EN 60835-3-13:1996-07 | Methods of measurement for equipment used in digital microwave radio transmission systems Part 3: measurements on satellite earth stations Section 13: VSAT systems |
| EN 60835-3-14:1996-07 | Methods of measurement for equipment used in digital microwave radio transmission systems Part 3: measurements on satellite earth stations Section 14: Earth stations for satellite news gathering (SNG) |
| EN 60835-3-6:1996-07 | Methods of measurement for equipment used in digital microwave radio transmission systems Part 2: Measurements on terrestrial radio-relay systems Section 6: High power amplifiers |
| EN 62272-2:2007-04 | Digital Radio Mondiale (DRM) Part 2: Digital radio in the bands below 30 MHz - Methods of measurement for DRM transmitters |
| EN 62273-1:2007-04 | Methods of measurement for radio transmitters Part 1: Performance characteristics of terrestrial digital television transmitters |
| CEI/CT 205 | Sistemi bus per edifici (ex CT 83) |
| R205-007:1996-10 | Home and Building Electronic Systems (HBES) Technical Report 7: Aspects of application - Application Layer |
| R205-010:1996-10 | Home and Building Electronic Systems (HBES) Technical Report 10: Interfaces - Medium Interface, Twisted Pair, Class 1 |
| CEI/CT 301/22G | Azionamenti elettrici (ex CT 301, SC 22G) |
| EN 61491:1998-08 | Electrical equipment of industrial machines - Serial data link for real-time communication between controls and drives |
| <i>La presente Norma è sostituita parzialmente dalle CEI EN 61158-2:2008-11 (CEI 65-131), CEI EN 61158-3-16:2008-09 (CEI 65-126), CEI EN 61158-4-16:2008-11 (CEI 65-142), CEI EN 61158-5-16:2009-03 (CEI 65-162); CEI EN 61158-6-16:2009-04 (CEI 65-180); CEI EN 61784-1:2009-02 (CEI 65-147); CEI EN 61800-7-1:2008-10 (CEI 301-7), CEI EN 61800-7-204:2009-02 (CEI 301-10), CEI EN 61800-7-304:2009-05 (CEI 301-11).</i> | |
| CEI/CT 309 | Componentistica elettronica (ex CT 40, 47, 52/91) |
| CECC 23100-801:1998-02 | Capability Detail Specification: Single and double-sided printed boards with plain holes |
| CECC 23200-801:1998-02 | Capability Detail Specification: Single and double-sided printed boards with plated-through holes |
| CECC 23300-801:1998-02 | Capability Detail Specification: Multi-layer printed boards |
| CECC 30801-802:2005-05 + EC:2005-06 | Detail specification: Fixed tantalum surface mount capacitors with solid electrolyte and porous anode: Extended range |
| CECC 32101-804:2001-05 | Detail specification: Fixed multilayer ceramic surface mounting capacitors, class 1, sub-class 1B, type CG, climatic category 55/125/56, assessment level EZ, with failure rate levels |
| CECC 32101-805:2001-05 | Detail specification: Fixed multilayer ceramic surface mounting capacitors, class 2, sub-classes 2C1 and 2R1, climatic category 55/125/56, assessment level EZ, with failure rate levels |
| CECC 40201-801:1998-05 | Detail specification: Fixed power resistors - Wirewound vitreous enamel - Stability class 5 |
| CECC 40402-801:2000-02 | Detail Specification: Fixed low power wire wound surface mounting (SMD) resistors |
| CECC 265001:1998-09 | Technology Approval Schedule: Film and hybrid integrated circuits |
| EN 50389:2005-09 | Space product assurance - Wire-wrapping of high-reliability electrical connections |
| EN 60115-1:2001-09 | Fixed resistors for use in electronic equipment Part 1: Generic specification |
| EN 60115-1/A1:2001-09 | Fixed resistors for use in electronic equipment Part 1: Generic specification |
| EN 60115-1/A11:2007-12 | Fixed resistors for use in electronic equipment Part 1: Generic specification |
| EN 60115-9:2004-02 | Fixed resistors for use in electronic equipment Part 9: Sectional specification - Fixed surface mount resistor networks with individually measurable resistors |
| EN 60115-9-1:2004-02 | Fixed resistors for use in electronic equipment Part 9-1: Blank detail specification - Fixed surface mount resistor networks with individually measurable resistors - Assessment level EZ |
| EN 60122-1:2002-12 | Quartz crystal units of assessed quality Part 1: Generic specification |
| EN 60122-3:2001-10 | Quartz crystal units of assessed quality Part 3: Standard outlines and lead connections |

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| EN 60133:2001-03 | Dimensions of pot-cores made of magnetic oxides and associated parts |
| EN 60139:2001-03 | Preparation of outline drawings for cathode-ray tubes, their components, connections and gauges |
| EN 60191-3:1999-11 | Mechanical standardization of semiconductor devices Part 3: General rules for the preparation of outline drawings of integrated circuits |
| EN 60191-4:1999-10 | Mechanical standardization of semiconductor devices Part 4: Coding system and classification into forms of package outlines for semiconductor device packages |
| EN 60191-4/A1:2002-02 | Mechanical standardization of semiconductor devices Part 4: Coding system and classification into forms of package outlines for semiconductor device packages |
| EN 60191-4/A2:2002-10 | Mechanical standardization of semiconductor devices Part 4: Coding system and classification into forms of package outlines for semiconductor device packages |
| EN 60191-6:2004-12 | Mechanical standardization of semiconductor devices Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages |
| EN 60191-6-10:2003-12 | Mechanical standardization of semiconductor devices Part 6-10: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - General rules for the dimensions of P-VSON |
| EN 60191-6-12:2002-07 | Mechanical standardization of semiconductor devices Part 6-12: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for fine-pitch land grid array (FLGA) - Rectangular type |
| EN 60191-6-13:2007-11 | Mechanical standardization of semiconductor devices Part 6-13: Design guideline of open-top-type sockets for Fine-pitch Ball Grid Array and Fine-pitch Land Grid Array (FBGA/FLGA) |
| EN 60191-6-2:2002-02 | Mechanical standardization of semiconductor devices Part 6-2: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Unit design guide for 1,50 mm, 1,27 mm and 1,00 mm pitch ball and column terminal packages |
| EN 60191-6-3:2000-12 | Mechanical standardization of semiconductor devices Part 6-3: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Measuring methods for package dimensions of quad flat packs (QFP) |
| EN 60191-6-4:2003-07 | Mechanical standardization of semiconductor devices Part 6-4: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Measuring methods for package dimensions of ball grid array (BGA) |
| EN 60191-6-5:2001-10 | Mechanical standardization of semiconductor devices Part 6-5: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for fine-pitch ball grid array (FBGA) |
| EN 60191-6-6:2001-07 | Mechanical standardization of semiconductor devices Part 6-6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for fine pitch land grid array (FLGA) |
| EN 60191-6-8:2001-10 | Mechanical standardization of semiconductor devices Part 6-8: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for glass sealed ceramic quad flatpack (G-QFP) |
| EN 60205:2006-07 | Calculation of the effective parameters of magnetic piece parts |
| EN 60286-5:2004-05 | Packaging of components for automatic handling Part 5: Matrix trays |
| EN 60286-6:2004-03 | Packaging of components for automatic handling Part 6: Bulk case packaging for surface mounting components |
| EN 60368-1:2000-04 | Piezoelectric filters of assessed quality Part 1: Generic specification |
| EN 60368-1/A1:2004-09 | Piezoelectric filters of assessed quality Part 1: Generic specification |
| EN 60368-1/EC:2001-02 | Piezoelectric filters of assessed quality Part 1: Generic specification |
| EN 60368-2-2:1999-02 | Piezoelectric filters Part 2: Guide to the use of piezoelectric filters Section 2: Piezoelectric ceramic filters |
| EN 60368-3:2001-10 | Piezoelectric filters of assessed quality Part 3: Standard outlines and lead connections |
| EN 60368-4:2000-12 | Piezoelectric filters of assessed quality Part 4: Sectional specification - Capability approval |
| EN 60368-4/EC:2001-02 | Piezoelectric filters of assessed quality Part 4: Sectional specification - Capability approval |
| EN 60368-4-1:2000-12 | Piezoelectric filters of assessed quality Part 4-1: Blank detail specification - Capability approval |
| EN 60368-4-1/EC:2001-02 | Piezoelectric filters of assessed quality Part 4-1: Blank detail specification - Capability approval |
| EN 60384-2:2005-12 | Fixed capacitors for use in electronic equipment Part 2: Sectional specification - Fixed metallized polyethylene-terephthalate film dielectric d.c. capacitors |
| EN 60384-2-1:2005-12 | Fixed capacitors for use in electronic equipment Part 2-1: Blank detail specification - Fixed metallized polyethylene-terephthalate film dielectric d.c. capacitors - Assessment levels E and EZ |

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| EN 60384-3-1:2006-12 | Fixed capacitors for use in electronic equipment Part 3-1: Blank detail specification: Surface mount fixed tantalum electrolytic capacitors with manganese dioxide solid electrolyte - Assessment level E |
| EN 60384-4-1:2007-05 | Fixed capacitors for use in electronic equipment Part 4-1: Blank detail specification - Fixed aluminium electrolytic capacitors with non-solid electrolyte - Assessment level EZ |
| EN 60384-4-2:2007-05 | Fixed capacitors for use in electronic equipment Part 4-2: Blank detail specification - Fixed aluminium electrolytic capacitors with solid (MnO ₂) electrolyte - Assessment level EZ |
| EN 60384-8:2005-06 | Fixed capacitors for use in electronic equipment Part 8: Sectional specification - Fixed capacitors of ceramic dielectric, Class 1 |
| EN 60384-8-1:2005-06 | Fixed capacitors for use in electronic equipment Part 8-1: Blank detail specification - Fixed capacitors of ceramic dielectric, Class 1 - Assessment level EZ |
| EN 60384-9:2005-06 | Fixed capacitors for use in electronic equipment Part 9: Sectional specification - Fixed capacitors of ceramic dielectric, Class 2 |
| EN 60384-9-1:2005-06 | Fixed capacitors for use in electronic equipment Part 9-1: Blank detail specification - Fixed capacitors of ceramic dielectric, Class 2 - Assessment level EZ |
| EN 60384-11-1:2008-04 | Fixed capacitors for use in electronic equipment Part 11-1: Blank detail specification - Fixed polyethylene-terephthalate film dielectric metal foil d.c. capacitors - Assessment level EZ |
| EN 60384-14:2005-08 | Fixed capacitors for use in electronic equipment Part 14: Sectional specification - Fixed capacitors for electromagnetic interference suppression and connection to the supply mains |
| EN 60384-14-1:2005-08 | Fixed capacitors for use in electronic equipment Part 14-1: Blank detail specification - Fixed capacitors for electromagnetic interference suppression and connection to the supply mains - Assessment level D |
| EN 60384-14-2:2004-11 | Fixed capacitors for use in electronic equipment Part 14-2: Blank detail specification - Fixed capacitors for electromagnetic interference suppression and connection to the supply mains - Safety tests only |
| EN 60384-14-3:2004-11 | Fixed capacitors for use in electronic equipment Part 14-3: Blank detail specification - Fixed capacitors for electromagnetic interference suppression and connection to the supply mains - Assessment level DZ |
| EN 60384-16:2005-12 | Fixed capacitors for use in electronic equipment Part 16: Sectional specification - Fixed metallized polypropylene film dielectric d.c. capacitors |
| EN 60384-16-1:2005-12 | Fixed capacitors for use in electronic equipment Part 16-1: Blank detail specification - Fixed metallized polypropylene film dielectric d.c. capacitors - Assessment levels E and EZ |
| EN 60384-17:2005-12 | Fixed capacitors for use in electronic equipment Part 17: Sectional specification - Fixed metallized polypropylene film dielectric a.c. and pulse capacitors |
| EN 60384-17-1:2005-12 | Fixed capacitors for use in electronic equipment Part 17-1: Blank detail specification - Fixed metallized polypropylene film dielectric a.c. and pulse capacitors - Assessment levels E and EZ |
| EN 60384-18-1:2007-05 | Fixed capacitors for use in electronic equipment Part 18-1: Blank detail specification - Fixed aluminium electrolytic surface mount capacitors with solid (MnO ₂) electrolyte - Assessment level EZ |
| EN 60384-18-2:2007-05 | Fixed capacitors for use in electronic equipment Part 18-2: Blank detail specification - Fixed aluminium electrolytic surface mount capacitors with non-solid electrolyte - Assessment level EZ |
| EN 60384-20-1:2008-04 | Fixed capacitors for use in electronic equipment Part 20-1: Blank detail specification - Fixed metallized polyphenylene sulfide film dielectric surface mount d.c. capacitors - Assessment level EZ |
| EN 60384-21:2004-11 | Fixed capacitors for use in electronic equipment Part 21: Sectional specification: Fixed surface mount multilayer capacitors of ceramic dielectric, Class 1 |
| EN 60384-21-1:2004-11 | Fixed capacitors for use in electronic equipment Part 21-1: Blank detail specification: Fixed surface mount multilayer capacitors of ceramic dielectric, Class 1, Assessment level EZ |
| EN 60384-22:2004-11 | Fixed capacitors for use in electronic equipment Part 22: Sectional specification: Fixed surface mount multilayer capacitors of ceramic dielectric, Class 2 |
| EN 60384-22-1:2004-11 | Fixed capacitors for use in electronic equipment Part 22-1: Blank detail specification: Fixed surface mount multilayer capacitors of ceramic dielectric, Class 2, Assessment level EZ |
| EN 60384-23:2005-02 | Fixed capacitors for use in electronic equipment Part 23: Sectional specification: Fixed surface mount metallized polyethylene naphthalate film dielectric d.c. capacitors |
| EN 60384-23-1:2005-02 | Fixed capacitors for use in electronic equipment Part 23-1: Blank detail specification: Fixed surface mount metallized polyethylene naphthalate film dielectric d.c. capacitors - Assessment level EZ |
| EN 60384-24-1:2006-08 | Fixed capacitors for use in electronic equipment Part 24-1: Blank detail specification - Surface mount fixed tantalum electrolytic capacitors with conductive polymer solid electrolyte - Assessment level EZ |

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| EN 60384-25-1:2006-08 | Fixed capacitors for use in electronic equipment Part 25-1: Blank detail specification - Surface mount fixed aluminium electrolytic capacitors with conductive polymer solid electrolyte - Assessment level EZ |
| EN 60401-1:2005-02 | Terms and nomenclature for cores made of magnetically soft ferrites Part 1: Terms used for physical irregularities |
| EN 60401-2:2003-06 | Terms and nomenclature for cores made of magnetically soft ferrites Part 2: Reference of dimensions |
| EN 60401-3:2003-12 | Terms and nomenclature for cores made of magnetically soft ferrites Part 3: Guide on the format of data appearing in manufacturer's catalogues of transformer and inductor cores |
| EN 60424-1:1999-08 | Ferrite cores - Guide on the limits of surface irregularities Part 1: General specification |
| EN 60424-2:1997-10 | Guidance of the limits of surface irregularities of ferrite cores Part 2: RM-cores |
| EN 60424-3:1999-08 | Ferrite cores - Guide on the limits of surface irregularities Part 3: ETD-cores and E-cores |
| EN 60424-4:2001-05 | Ferrite cores - Guide on the limits of surface irregularities Part 4: Ring cores |
| EN 60444-1:1997-04 | Measurement of quartz crystal unit parameters by zero phase technique in a pi-network Part 1: Basic method for the measurement of resonance frequency and resonance resistance of quartz crystal units by zero phase technique in a pi-network |
| EN 60444-1/A1:1999-10 | Measurement of quartz crystal unit parameters by zero phase technique in a pi-network Part 1: Basic method for the measurement of resonance frequency and resonance resistance of quartz crystal units by zero phase technique in a pi-network |
| EN 60444-2:1997-04 | Measurement of quartz crystal unit parameters by zero phase technique in a pi-network Part 2: Phase offset method for measurement of motional capacitance of quartz crystal units |
| EN 60444-3:1997-04 | Measurement of quartz crystal unit parameters by zero phase technique in a pi-network Part 3: Basic method for the measurement of two terminal parameters of quartz crystal units up to 200 MHz by phase technique in a pi-network with compensation of the parallel capacitance C_0 |
| EN 60444-4:1997-04 | Measurement of quartz crystal unit parameters by zero phase technique in a pi-network Part 4: Method for the measurement of the load resonance frequency f_L , load resonance resistance R_L and the calculation of other derived values of quartz crystal units, up to 30 MHz |
| EN 60444-5:1997-04 | Measurement of quartz crystal unit parameters Part 5: Methods for the determination of equivalent electrical parameters using automatic network analyzer techniques and error correction |
| EN 60444-6:1997-04 | Measurement of quartz crystal unit parameters Part 6: Measurement of drive level dependence (DLD) |
| EN 60444-7:2004-06 | Measurement of quartz crystal unit parameters Part 7: Measurement of activity and frequency dips of quartz crystal units |
| EN 60444-8:2003-10 | Measurement of quartz crystal unit parameters Part 8: Test fixture for surface mounted quartz crystal units |
| EN 60444-9:2007-04 | Measurement of quartz crystal unit parameters Part 9: Measurement of spurious resonances of piezoelectric crystal units |
| EN 60539-1:2008-05 | Directly heated negative temperature coefficient thermistors Part 1: Generic specification |
| EN 60539-2:2004-02 | Directly heated negative temperature coefficient thermistors Part 2: Sectional specification - Surface mount negative temperature coefficient thermistor |
| EN 60556:2006-06 | Measuring methods for properties of gyromagnetic materials intended for application at microwave frequencies |
| EN 60679-1:2007-06 | Quartz crystal controlled oscillators of assessed quality Part 1: Generic specification |
| EN 60679-3:2001-10 | Quartz crystal controlled oscillators of assessed quality Part 3: Standard outlines and lead connections |
| EN 60679-4:1998-02 | Quartz crystal controlled oscillators of assessed quality Part 4: Sectional Specification - Capability approval |
| EN 60679-4-1:1998-04 | Quartz crystal controlled oscillators of assessed quality Part 4-1: Blank detail specification - Capability approval |
| EN 60679-5:1998-08 | Quartz crystal controlled oscillators of assessed quality Part 5: Sectional specification - Qualification approval |
| EN 60679-5-1:1998-08 | Quartz crystal controlled oscillators of assessed quality Part 5-1: Blank detail specification - Qualification approval |
| EN 60738-1-1:2008-04 | Thermistors - Directly heated positive step-function temperature coefficient - Part 1-1: Blank detail specification - Current limiting application - Assessment level EZ |

Da utilizzare congiuntamente alla EN 60738-1.

EN 60738-1-2:2008-04 Thermistors - Directly heated positive step-function temperature coefficient
Part 1-2: Blank detail specification - Heating element application - Assessment level EZ

Da utilizzare congiuntamente alla EN 60738-1.

EN 60738-1-3:2008-04 Thermistors - Directly heated positive step-function temperature coefficient
Part 1-3: Blank detail specification - Inrush current application - Assessment level EZ

Da utilizzare congiuntamente alla EN 60738-1.

EN 60738-1-4:2008-04 Thermistors - Directly heated positive step-function temperature coefficient
Part 1-4: Blank detail specification - Sensing application - Assessment level EZ

Da utilizzare congiuntamente alla EN 60738-1.

EN 60740-1:2005-10 Laminations for transformers and inductors
Part 1: Mechanical and electrical characteristics

EN 60747-5-1:2001-07 Discrete semiconductor devices and integrated circuits
Part 5-1: Optoelectronic devices - General

EN 60747-5-1/A1:2002-02 Discrete semiconductor devices and integrated circuits
Part 5-1: Optoelectronic devices - General

EN 60747-5-1/A2:2002-05 Discrete semiconductor devices and integrated circuits
Part 5-1: Optoelectronic devices - General

EN 60747-5-2:2001-07 Discrete semiconductor devices and integrated circuits
Part 5-2: Optoelectronic devices - Essential ratings and characteristics

EN 60747-5-2/A1:2002-05 Discrete semiconductor devices and integrated circuits
Part 5-2: Optoelectronic devices - Essential ratings and characteristics

EN 60747-5-3:2001-07 Discrete semiconductor devices and integrated circuits
Part 5-3: Optoelectronic devices - Measuring methods

EN 60747-5-3/A1:2002-05 Discrete semiconductor devices and integrated circuits
Part 5-3: Optoelectronic devices - Measuring methods

EN 60747-15:2004-01 Discrete semiconductor devices
Part 15: Isolated power semiconductor devices

EN 60747-16-1:2002-02 Semiconductor devices
Part 16-1: Microwave integrated circuits - Amplifiers

EN 60747-16-1/A1:2007-02 Semiconductor devices
Part 16-1: Microwave integrated circuits - Amplifiers

EN 60747-16-10:2004-09 Semiconductor devices
Part 16-10: Technology Approval Schedule (TAS) for monolithic microwave integrated circuits

EN 60747-16-3:2002-07 Semiconductor devices
Part 16-3: Microwave integrated circuits - Frequency converters

EN 60747-16-4:2004-09 Semiconductor devices
Part 16-4: Microwave integrated circuits - Switches

EN 60749-24:2004-04 Semiconductor devices - Mechanical and climatic test methods
Part 24: Accelerated moisture resistance - Unbiased HAST

EN 60749-33:2004-04 Semiconductor devices - Mechanical and climatic test methods
Part 33: Accelerated moisture resistance - Unbiased autoclave

EN 60749-34:2004-04 Semiconductor devices - Mechanical and climatic test methods
Part 34: Power cycling

EN 60749-35:2006-09 Semiconductor devices - Mechanical and climatic test methods
Part 35: Acoustic microscopy for plastic encapsulated electronic components

EN 60758:2005-02 Synthetic quartz crystal - Specifications and guide to the use

EN 60852-4:1996-08 Outline dimensions of transformers and inductors for use in telecommunication and electronic equipment
Part 4: Transformers and inductors using YUI-2 laminations

EN 60862-1:2003-08 Surface acoustic wave (SAW) filters of assessed quality
Part 1: Generic specification

EN 60862-2:2002-09 Surface acoustic wave (SAW) filters of assessed quality
Part 2: Guidance on use

EN 60862-3:2003-12 Surface acoustic wave (SAW) filters of assessed quality
Part 3: Standard outlines

EN 60915:2007-09 + EC:2009-04 Capacitors and resistors for use in electronic equipment - Preferred dimensions of shaft ends, bushes and for the mounting of single-hole, bush-mounted, shaft-operated electronic components

EN 60938-1:1999-12 Fixed inductors for electromagnetic interference suppression
Part 1: Generic specification

EN 60938-1/A1:2007-02 Fixed inductors for electromagnetic interference suppression
Part 1: Generic specification

EN 60938-2:1999-12 Fixed inductors for electromagnetic interference suppression
Part 2: Sectional specification

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| EN 60938-2/A1:2007-02 | Fixed inductors for electromagnetic interference suppression Part 2: Sectional specification |
| EN 60938-2-1:1999-12 | Fixed inductors for electromagnetic interference suppression Part 2-1: Blank detail specification - Inductors for which safety tests are required - Assessment level D |
| EN 60938-2-2:1999-12 | Fixed inductors for electromagnetic interference suppression Part 2-2: Blank detail specification - Inductors for which safety tests are required (only) |
| EN 60939-2-1:2004-12 | Complete filter units for radio interference suppression Part 2-1: Blank detail specification - Passive filter units for electromagnetic interference suppression - Filters for which safety tests are required (Assessment level D/DZ) |
| EN 60939-2-2:2004-12 | Complete filter units for radio interference suppression Part 2-2: Blank detail specification - Passive filter units for electromagnetic interference suppression - Filters for which safety tests are required (Safety tests only) |
| EN 61007:1997-05 | Transformers and inductors for use in electronic and telecommunication equipment - Measuring methods and test procedures |
| EN 61019-1:2005-01 | Surface acoustic wave (SAW) resonators Part 1: Generic specification |
| EN 61019-2:2005-06 | Surface acoustic wave (SAW) resonators Part 2: Guide to the use |
| EN 61021-1:1997-04 | Laminated core packages for transformers and inductors used in telecommunication and electronic equipment Part 1: Dimensions |
| EN 61021-2:1997-04 | Laminated core packages for transformers and inductors for use in telecommunication and electronic equipment Part 2: Electrical characteristics for cores using YEE 2 laminations |
| EN 61185:2005-06 | Magnetic oxide cores (ETD-cores) intended for use in power supply applications - Dimensions |
| EN 61188-1-1:1997-10 | Printed boards and assemblies - Design and use Part 1: Generic requirements Section 1: Flatness considerations for electronic assemblies |
| EN 61189-1:1997-04 | Test methods for electrical materials, printed boards and interconnection structures and assemblies Part 1: General test methods and methodology |
| EN 61189-1/A1:2001-10 | Test methods for electrical materials, printed boards and other interconnection structures and assemblies Part 1: General test methods and methodology |
| EN 61240:1997-04 | Piezoelectric devices - Preparation of outline drawings of surface-mounted devices (SMD) for frequency control and selection - General rules |
| EN 61247:1997-05 | PM cores made of magnetic oxides and associated parts - Dimensions |
| EN 61248-1:1997-08 | Transformers and inductors for use in electronic and telecommunication equipment Part 1: Generic specification |
| EN 61248-2:1997-08 | Transformers and inductors for use in electronic and telecommunication equipment Part 2: Sectional specification for signal transformers on the basis of the capability approval procedure |
| EN 61248-3:1997-08 | Transformers and inductors for use in electronic and telecommunication equipment Part 3: Sectional specification for power transformers on the basis of the capability approval procedure |
| EN 61248-4:1997-08 | Transformers and inductors for use in electronic and telecommunication equipment Part 4: Sectional specification for power transformers for switched mode power supplies (SMPS) on the basis of the capability approval procedure |
| EN 61248-5:1997-08 | Transformers and inductors for use in electronic and telecommunication equipment Part 5: Sectional specification for pulse transformers on the basis of the capability approval procedure |
| EN 61248-6:1997-08 | Transformers and inductors for use in electronic and telecommunication equipment Part 6: Sectional specification for inductors on the basis of the capability approval procedure |
| EN 61248-7:1997-08 | Transformers and inductors for use in electronic and telecommunication equipment Part 7: Sectional specification for high-frequency inductors and intermediate frequency transformers on the basis of the capability approval procedure |
| EN 61249-2-12:1999-04 | Materials for printed boards and other interconnecting structures Part 2-12: Sectional specification set for reinforced base materials, clad and unclad - Epoxide non-woven aramid laminate of defined flammability, copper-clad |
| EN 61249-2-13:1999-04 | Materials for printed boards and other interconnecting structures Part 2-13: Sectional specification set for reinforced base materials, clad and unclad - Cyanate ester non-woven aramid laminate of defined flammability, copper clad |
| EN 61249-2-18:2002-03 | Materials for printed boards and other interconnection structures Part 2-18: Reinforced base materials, clad and unclad - Polyester non-woven fibreglass reinforced laminated sheet of defined flammability (vertical burning test), copper-clad |
| EN 61249-2-19:2002-02 | Materials for printed boards and other interconnection structures Part 2-19: Sectional specification set for reinforced base materials, clad and unclad - Epoxide cross-plyed linear fibreglass-reinforced laminated sheet of defined flammability (vertical burning test) copper clad |
| EN 61249-2-4:2002-03 | Materials for printed boards and other interconnecting structures Part 2-4: Reinforced base materials clad and unclad - Polyester non-woven/woven fibreglass laminated sheet of defined flammability (vertical burning test), copper-clad |
| EN 61249-3-3:1999-04 | Materials for printed boards and other interconnecting structures Part 3-3: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) - Adhesive coated flexible polyester film |

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| EN 61249-3-4:1999-04 | Materials for printed boards and other interconnecting structures Part 3-4: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) - Adhesive coated flexible polyimide film |
| EN 61249-3-5:1999-04 | Materials for printed boards and other interconnecting structures Part 3-5: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) - Transfer adhesive films |
| EN 61249-8-8:1997-08 | Materials for interconnection structures Part 8: Sectional specification set for non-conductive films and coatings Section 8: Temporary polymer coatings |
| EN 61332:2005-12 | Soft ferrite material classification |
| EN 61333:1998-04 | Marking on U and E ferrite cores |
| EN 61337-1:2004-12 | Filters using waveguide type dielectric resonators of assessed quality Part 1: Generic specification |
| EN 61337-2:2004-10 | Filters using waveguide type dielectric resonators Part 2: Guidance for use |
| EN 61338-1:2005-01 | Waveguide type dielectric resonators Part 1: Generic specification |
| EN 61338-1-3:2000-03 | Waveguide type dielectric resonators Part 1-3: General information and test conditions - Measurement method of complex relative permittivity for dielectric resonator materials at microwave frequency |
| EN 61338-1-4:2006-02 | Waveguide type dielectric resonator Part 1-4: General information and test conditions - Measurement method of complex relative permittivity for dielectric resonator materials at millimeter-wave frequency |
| EN 61338-2:2004-09 | Waveguide type dielectric resonators Part 2: Guide to the use of waveguide type dielectric resonators |
| EN 61338-4:2005-05 | Waveguide type dielectric resonators Part 4: Sectional specification |
| EN 61338-4-1:2005-05 | Waveguide type dielectric resonators Part 4-1: Blank detail specification |
| EN 61596:1997-05 | Magnetic oxide EP-cores and associated parts for use in inductors and transformers - Dimensions |
| EN 61605:2005-09 | Fixed inductors for use in electronic and telecommunication equipment - Marking codes |
| EN 61609:1999-02 | Microwave ferrite components - Guide for the drafting of specifications |
| EN 61631:2001-10 | Test method for the mechanical strength of cores made of magnetic oxides |
| EN 61747-2:1999-01 | Liquid crystal and solid-state display devices Part 2: Liquid crystal display modules - Sectional specification Sectional specification |
| EN 61747-2-1:2001-06 | Liquid crystal and solid-state display devices Part 2-1: Passive matrix monochrome LCD modules - Blank detail specification |
| EN 61747-2-2:2004-12 | Liquid crystal display devices Part 2-2: Matrix colour LCD modules - Blank detail specification |
| EN 61747-3:2006-09 | Liquid crystal display devices Part 3: Liquid crystal display (LCD) cells - Sectional specification Sectional specification |
| EN 61747-3-1:2006-10 | Liquid crystal display devices Part 3-1: Liquid crystal display (LCD) cells - Blank detail specification |
| EN 61747-4:1998-10 | Liquid crystal and solid-state display devices Part 4: Liquid crystal display modules and cells - Essential ratings and characteristics |
| EN 61747-4-1:2004-12 | Liquid crystal display devices Part 4-1: Matrix colour LCD modules - Essential ratings and characteristics |
| EN 61747-5:1998-09 | Liquid crystal and solid-state display devices Part 5: Environmental, endurance and mechanical test methods |
| EN 61747-6:2004-05 | Liquid crystal and solid-state display devices Part 6: Measuring methods for liquid crystal modules - Transmissive type |
| EN 61797-1:1996-12 | Transformers and inductors for use in telecommunication and electronic equipment - Main dimensions of coil formers Part 1: Coil formers for laminated cores |
| EN 61830:1998-02 | Microwave ferrite components - Measuring methods for major properties |
| EN 61837-1:1999-06 | Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections Part 1: Plastic moulded enclosures outlines |
| EN 61837-2:2000-11 | Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections Part 2: Ceramic enclosures |
| EN 61837-3:2000-11 | Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections Part 3: Metal enclosures |
| EN 61837-4:2004-11 | Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections Part 4: Hybrid enclosure outlines |

Da utilizzare congiuntamente a: EN 61240:1997.

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| EN 61843:1997-08 | Measuring method for the level of intermodulation products generated in a gyromagnetic device |
| EN 61943:1999-08 | Integrated circuits - Manufacturing line approval application guideline |
| EN 61964:1999-05 | Integrated circuits - Memory devices pin configurations |
| EN 61965:2003-10 | Mechanical safety of cathode ray tubes |
| EN 61967-1:2002-06 | Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz Part 1: General conditions and definitions |
| EN 61967-4:2002-06 | Integrated circuits - Measurement of electromagnetic emissions, 150 KHz to 1 GHz Part 4: Measurement of conducted emissions - 1 ohm/150 ohm direct coupling method |
| EN 61967-4/A1:2006-02 | Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz Part 4: Measurement of conducted emissions - 1 ohm/150 ohm direct coupling method |
| EN 61967-4/A1/EC:2006-12 | Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz Part 4: Measurement of conducted emissions - 1 ohm/150 ohm direct coupling method |
| EN 61967-6:2002-10 | Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz Part 6: Measurement of conducted emission, magnetic probe method |
| EN 61967-6/A1:2008-05 | Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz Part 6: Measurement of conducted emissions - Magnetic probe method |
| EN 61988-2-1:2002-12 | Plasma display panels Part 2-1: Measuring methods - Optical |
| EN 61988-3-1:2005-11 | Plasma Display Panels Part 3-1: Mechanical interface |
| EN 62024-1:2008-05 (+ IEC 62024-1/EC1:2008-07) | High frequency inductive components - Electrical characteristics and measuring methods Part 1: Nanohenry range chip inductor |
| EN 62025-1:2007-08 | High frequency inductive components - Non-electrical characteristics and measuring methods Part 1: Fixed, surface mounted inductor for use in electronic and telecommunication equipment |
| EN 62025-2:2005-03 | High frequency inductive components - Non-electrical characteristics and measuring methods Part 2: Test methods for non-electrical characteristics |
| EN 62044-1:2002-08 | Cores made of soft magnetic materials - Measuring methods Part 1: Generic specification |
| EN 62044-2:2005-04 | Cores made of magnetically soft ferrites - Measuring methods Part 2: Magnetic properties at low excitation level |
| EN 62044-3:2001-05 | Cores made of soft magnetic materials - Measuring methods Part 3: Magnetic properties at high excitation level |
| EN 62047-2:2006-09 | Semiconductor devices - Micro-electromechanical devices Part 2: Tensile testing methods of thin film materials |
| EN 62047-3:2006-09 | Semiconductor devices - Micro-electromechanical devices Part 3: Thin film standard test piece for tensile-testing |
| EN 62211:2004-01 | Inductive components - Reliability management |
| EN 62258-2:2005-06 | Semiconductor die products Part 2: Exchange data formats |
| EN 62258-5:2006-09 | Semiconductor die products Part 5: Requirements for information concerning electrical simulation |
| EN 62258-6:2006-09 | Semiconductor die products Part 6: Requirements for information concerning thermal simulation |
| EN 62276:2005-12 | Single crystal wafers for surface acoustic wave (SAW) device applications - Specifications and measuring methods |
| EN 62317-1:2007-08 | Ferrite cores - Dimensions Part 1: General specification |
| EN 62317-4:2005-12 | Ferrite cores - Dimensions Part 4: RM-cores made of ferrite and associated parts |
| EN 62317-7:2005-11 | Ferrite cores - Dimensions Part 7: EER-cores |
| EN 62317-8:2006-11 | Ferrite cores - Dimensions Part 8: E-cores |
| EN 62317-9:2006-09 | Ferrite cores - Dimensions Part 9: Planar cores |
| EN 62317-9/A1:2007-03 | Ferrite cores - Dimensions Part 9: Planar cores |
| EN 62317-13:2008-06 | Ferrite cores - Dimensions Part 13: PQ-cores for use in power supply applications |
| EN 62319-1:2005-03 | Polymeric thermistors - Directly heated positive step function temperature coefficient Part 1: Generic specification |
| EN 62319-1-1:2005-03 | Polymeric thermistors - Directly heated positive step function temperature coefficient Part 1-1: Blank detail specification - Current limiting application |
| EN 62323:2005-06 | Dimensions of half pot -cores made of ferrite for inductive proximity switches |

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|---|---|
| EN 62326-4:1997-01 | Printed boards Part 4: Rigid multilayer printed boards with interlayer connections -Sectional specification Sectional specification |
| EN 62326-4-1:1997-01 | Printed boards Part 4: Rigid multilayer printed boards with interlayer connections - Sectional specification Section 1: Capability detail specification - Performance levels A, B and C |
| EN 62333-1:2006-07 | Noise suppression sheet for digital devices and equipment - Part 1: Terms and definitions Part 1: Terms and definitions |
| EN 62333-2:2006-07 | Noise suppression sheet for digital devices and equipment - Part 2: Measuring methods Part 2: Measuring methods |
| EN 62358:2004-07 | Ferrite cores - Standard inductance factor (AL) and its tolerance |
| <i>La presente Norma è sostituita parzialmente dalla EN 62317-8:2006-11, recepita attraverso l'annuncio su Ceinforma 04/2007.</i> | |
| EN 62373:2006-08 | Bias-temperature stability test for metal-oxide, semiconductor, field-effect transistors (MOSFET) |
| EN 62374:2007-10 | Semiconductor devices -Time Dependent Dielectric Breakdown (TDDB) test for gate dielectric films |
| EN 62391-2-1:2006-06 | Fixed electric double-layer capacitors for use in electronic equipment Part 2-1: Blank detail specification - Electric-double layer capacitors for power application - Assessment level EZ |
| EN 130200/A3:1998-03 | Sectional Specification: Fixed tantalum capacitors with non-solid or solid electrolyte |
| EN 130201/A2:1998-03 | Sectional Specification: Fixed tantalum capacitors with solid electrolyte porous anode |
| EN 130202:1998-03 | Blank Detail Specification: Fixed tantalum capacitors with non-solid electrolyte, porous anode (sub-family 2) |
| EN 130502:1998-03 | Blank Detail Specification: Fixed metallized polycarbonate film dielectric capacitors for direct current - Assessment level EZ |
| EN 130800:2000-10 | Sectional Specification: Tantalum surface mounting capacitors |
| EN 130800/A1:2003-08 | Sectional Specification: Tantalum surface mounting capacitors |
| EN 140101:2008-03 | Blank Detail Specification: Fixed low power film resistors |
| EN 140101-806:2008-03 | Detail Specification: Fixed low power film resistors - Metal film resistors on high grade ceramic, conformal coated or molded, axial or preformed leads |
| EN 140200/A1:2001-08 | Sectional Specification: Fixed power resistors |
| EN 140400:2003-12 | Sectional specification: Fixed low power surface mount (SMD) resistors |
| EN 140401:2002-05 | Blank Detail Specification: Fixed low power non wire-wound surface mounting (SMD) resistors |
| EN 140401-801:2007-09 | Detail specification: Fixed low power film SMD resistors - Rectangular - Stability classes 0,1; 0,25; 0,5; 1 |
| EN 140401-802:2007-09 | Detail specification: Fixed low power film SMD resistors - Rectangular - Stability classes 1; 2 |
| EN 140401-803:2007-09 | Detail specification: Fixed low power film SMD resistors - Cylindrical - Stability classes 0,05; 0,1; 0,25; 0,5; 1; 2 |
| EN 140401-804:2005-03 | Detail specification: Fixed low power non wire-wound high stability surface mount (SMD) resistors - Rectangular - Stability classes 0,1; 0,25 |
| EN 140402:1998-08 | Blank Detail Specification: Fixed low power wire wound surface mounting (SMD) resistors |
| EN 140402-801:2005-02 | Detail specification: Fixed low power wire-wound surface mount (SMD) resistors - Rectangular - Stability classes 0,5; 1; 2 |
| EN 153000:1998-04 | Generic specification: Discrete pressure contact power semiconductor devices (Qualification approval) |
| EN 165000-5:1997-12 | Film and hybrid integrated circuits Part 5: Procedure for qualification approval |
| ES 59002:1998-09 | General requirements for integrated circuits |
| ES 59006:1998-11 | Methods and draft standards for the dynamic characterization and testing of analog to digital converters (DYNAD) |
| ES 59008-4-1:2000-09 | Data requirements for semiconductor die Part 4-1: Specific requirements and recommendations - Test and quality |
| ES 59008-5-1:2001-03 | Data requirements for semiconductor die Part 5-1: Particular requirements and recommendations for die types - Bare die |
| ES 59008-5-2:2001-03 | Data requirements for semiconductor die Part 5-2: Particular requirements and recommendations for die types - Bare die with added connection structures |
| ES 59008-5-3:2001-11 | Data requirements for semiconductor die Part 5-3: Particular requirements and recommendations for die types - Minimally-packaged die |
| TR 62258-7:2007-10 | Semiconductor die products Part 7: XML schema for data exchange |

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|-----------------------|---|
| CLC/TC 49 | Piezoelectric devices for frequency control and selection (CECC SC) -Sciolto nel 2002 |
| EN 166100:1998-08 | Sectional Specification: Surface acoustic wave (SAW) filters |
| EN 166101:1999-02 | Blank Detail Specification: Surface Acoustic Wave (SAW) filters - Capability approval |
| EN 169000/A1:1998-02 | Generic Specification: Quartz crystal controlled oscillators |
| EN 170100:2001-08 | Sectional Specification: Waveguide type dielectric resonators |
| EN 170101:2001-08 | Blank detail Specification: Waveguide type dielectric resonators - Capacity approval |
| CLC/SC 51X | Magnetic components: Cores and soft magnetic materials (CECC WG 12A) - Sciolto nel 1998 |
| EN 125000:1997-12 | Generic Specification: Cores made of ferrite materials |
| CLC/BTTF 63-2 | Advanced technical ceramics - Sciolto nel 2003 |
| EN 50324-1:2002-05 | Piezoelectric properties of ceramic materials and components -- Part 1: Terms and definitions Part 1: Terms and definitions |
| EN 50324-2:2002-05 | Piezoelectric properties of ceramic materials and components Part 2: Methods of measurement - Low power |
| EN 50324-3:2002-05 | Piezoelectric properties of ceramic materials and components Part 3: Methods of measurement - High power |
| CLC/BTWG 69-2 | Compensated connectors for thermo-electric sensors - Sciolto nel 1997 |
| EN 50212:1996-05 | Connectors for thermoelectric sensors |
| CLC/BTTF 95-1 | Inspection of electrical installations in domestic accomodations - Sciolto nel 2003 |
| ES 59009:2000-03 | Inspection and testing of electrical installations in domestic properties |
| CLC/TC 107X | Process management for avionics |
| EN 50390:2004-07 | Space product assurance - The manual soldering of high-reliability electrical connections |
| CLC/BTTF 116-2 | Alcohol interlocks |
| EN 50436-1:2005-11 | Alcohol interlocks - Test methods and performance requirements Part 1: Part 1: Instruments for drink-driving-offender programs |
| EN 50436-2:2007-12 | Alcohol interlocks - Test methods and performance requirements Part 2: Instruments having a mouthpiece and measuring breath alcohol for general preventive use |
| CLC/TC 217 | Electronic Design Automation (EDA) - Sciolto nel 2003 |
| EN 61523-1:2002-01 | Delay and power calculation standards Part 1: Integrated circuit delay and power calculation systems |
| EN 61523-2:2002-08 | Delay and power calculation standards Part 2: Pre-layout delay calculation specification for CMOS ASIC libraries |
| EN 61690-1:2000-05 | Electronic Design Interchange Format (EDIF) - Version 3.0.0. Level 0 - Information model |
| EN 61690-2:2000-05 | Electronic Design Interchange Format (EDIF) Part 2: Version 4.0.0 |
| EN 61691-1:1997-09 | Design automation Part 1: VHDL language reference manual |
| EN 61691-2:2001-12 | Behavioural languages Part 2: VHDL multilogic system for model interoperability |
| EN 61691-3-2:2001-12 | Behavioural languages Part 3-2: Mathematical operation in VHDL |
| EN 61691-3-3:2001-12 | Behavioural languages Part 3-3: IEEE Standard VHDL Synthesis |
| EN 61926-1:2000-01 | Design automation Part 1: Standard test language for all systems Common/abbreviated test language for all systems (C/ATLAS) |
| EN 62014-1:2002-01 | Electronic design automation libraries Part 1: Input/Output buffer information specification (IBIS version 3.2) |
| ENV 50208-6:1997-06 | Data interchange format for Simulated and Measured Data (ISMD) |

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| ENV 50218:1996-02 | Description of a parametrized European mini test chip |
| ENV 50219:1996-02 | Description of reliability test structures of the European mini test chip |
| ENV 50247-1:1998-11 | Pinnacles Component Information Standard 1.2 - The PCIS tag library |
| ENV 50247-2:1998-11 | Pinnacles Component Information Standard 1.2 - The SGML declaration and SGML Document Type Definitions (DTDs) |
| ES 59011:2001-03 | Specification for the representation of Quality rules and metrics for Hardware and Software Design Languages |
| CLC/ WG QAP | |
| EN 100114-6/A1:1999-02 | CECC Quality assessment procedure for electronic components Part 6: Technology approval of manufacturers |
| IEC/TC 68 | Magnetic alloys and steels |
| EN 60404-2:1998-02 | Magnetic materials Part 2: Methods of measurement of the magnetic properties of electrical steel sheet and strip by means of an Epstein frame |
| EN 60404-2/A1:2008-07 + EC:2008-10 | Magnetic materials Part 2: Methods of measurement of the magnetic properties of electrical steel sheet and strip by means of an Epstein frame |
| EN 60404-4:1997-01 | Magnetic materials Part 4: Methods of measurement of d.c. magnetic properties of iron and steel |
| EN 60404-4/A1:2002-04 | Magnetic materials Part 4: Methods of measurement of d.c. magnetic properties of magnetically soft materials |
| EN 60404-5:2007-10 | Magnetic materials Part 5: Permanent magnet (magnetically hard) materials - Methods of measurement of magnetic properties |
| EN 60404-13:2007-10 | Magnetic materials Part 13: Methods of measurement of density, resistivity and stacking factor of electrical steel sheet and strip |
| EN 60404-14:2002-10 | Magnetic materials Part 14: Methods of measurement of the magnetic dipole moment of a ferromagnetic material specimen by the withdrawal or rotation method |